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From:	Secretary-General of the European Commission, signed by Mr Jordi AYET PUIGARNAU, Director
date of receipt:	14 March 2014
To:	Mr Uwe CORSEPIUS, Secretary-General of the Council of the European Union

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No. Cion doc.:	C(2014) 1642 final - Annex 1
Subject:	Annex to the Commission Delegated Directive amending, for the purposes of adapting to technical progress, Annex IV to Directive 2011/65/EU of the European Parliament and of the Council as regards an exemption for lead in solder in one interface of large area stacked die elements

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Delegations will find attached document C(2014) 1642 final - Annex 1.

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Encl.: C(2014) 1642 final - Annex 1



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ANNEX 1

## **ANNEX**

**to the**

**Commission Delegated Directive**

**amending, for the purposes of adapting to technical progress, Annex IV to Directive 2011/65/EU of the European Parliament and of the Council as regards an exemption for lead in solder in one interface of large area stacked die elements.**

## **ANNEX**

**to the**

### **Commission Delegated Directive**

**amending, for the purposes of adapting to technical progress, Annex IV to Directive 2011/65/EU of the European Parliament and of the Council as regards an exemption for lead in solder in one interface of large area stacked die elements.**

In Annex IV to Directive 2011/65/EU the following point 38 is added:

"38. Lead in solder in one interface of large area stacked die elements with more than 500 interconnects per interface which are used in X-ray detectors of computed tomography and X-ray systems

Expires on 31 December 2019. May be used after that date in spare parts for CT and X-ray systems placed on the market before 1 January 2020."